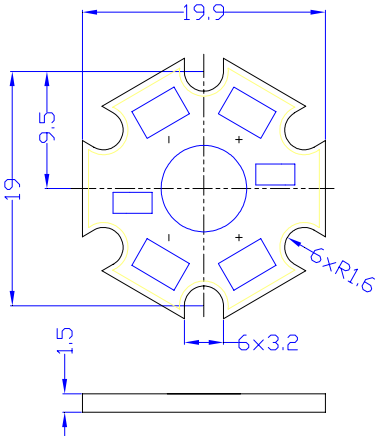

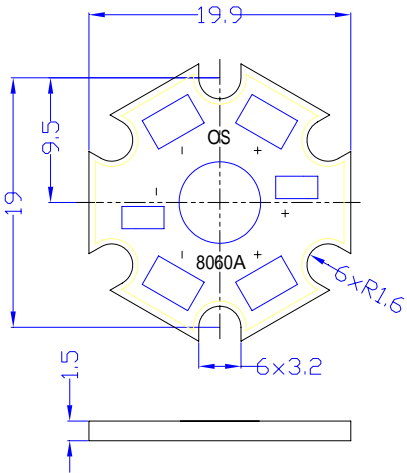

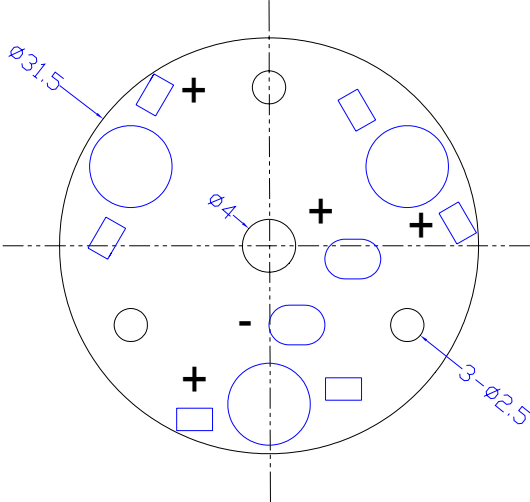

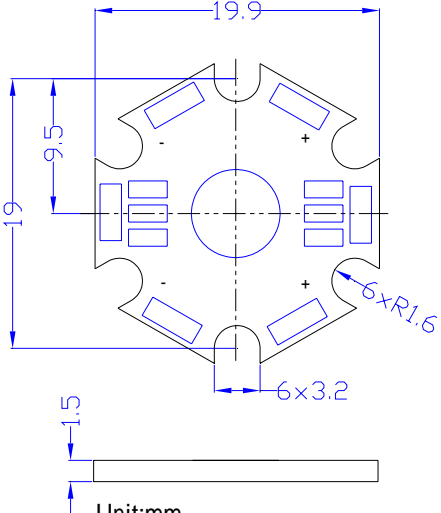

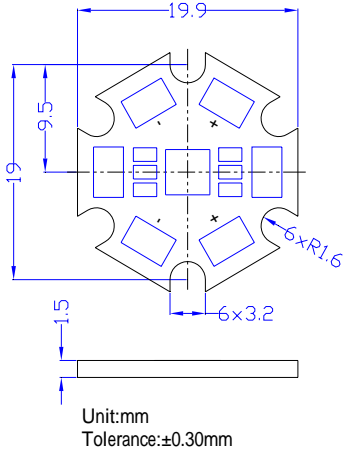
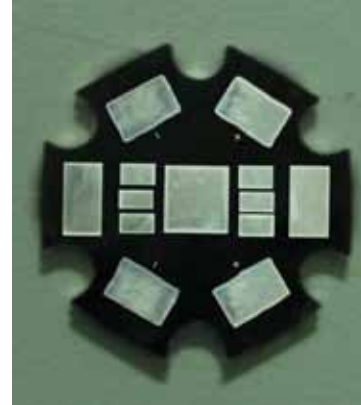
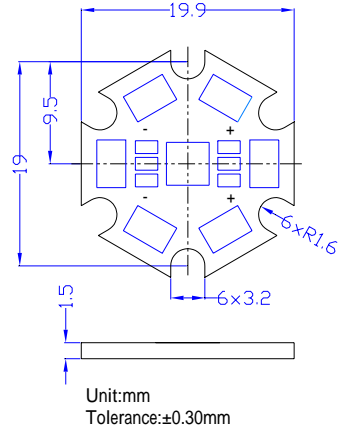

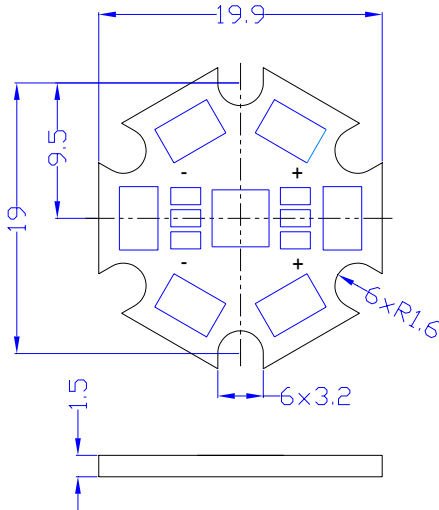
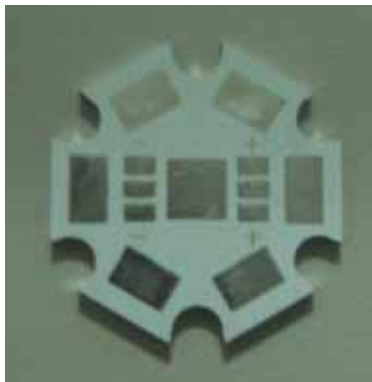


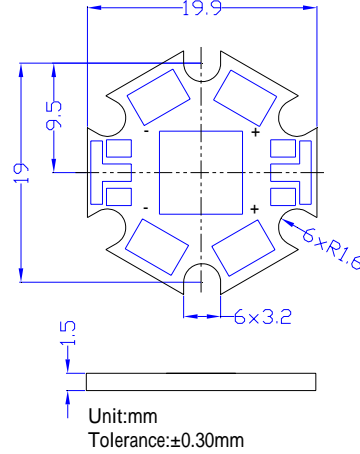

Heat Sink for Xeon Series					
Item	Part Number	Description	Dimension	Photo	Application
1W	OSMCPCB8060B	<ul style="list-style-type: none"> Aluminum metal-base copper-clad laminate PCB Design for Xeon 1 Power Series LED Base metal is 1.5mm Aluminum With NTCDC Thermally Conductive Dielectric Copper Circuit Foil is 35 μ m(1oz) Surface Finish is Black Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	 <p>Unit:mm Tolerance:±0.30mm</p>		Used for Xeon 1 Power Series, eg: OSW4XME1C1E
3W	OSMCPCB8060A	<ul style="list-style-type: none"> Aluminum metal-base copper-clad laminate PCB Design for Xeon 3 Power Series LED Base metal is 1.5mm Aluminum With HTCD Thermally Conductive Dielectric to suitable high power LED Copper Circuit Foil is 35 μ m(1oz) Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	 <p>Unit:mm Tolerance:±0.30mm</p>		Used for Xeon 3 Power Series, eg: OSW4XME3C1E

<p>3W</p>	<p>OSMCPCB8086D</p>	<ul style="list-style-type: none"> ● Aluminum metal-base copper-clad laminate PCB ● Design for 3pcs Xeon 1 Power Series LED ● Base metal is 1.5mm Aluminum ● With HTCD Thermally Conductive Dielectric to suitable high power LED ● Copper Circuit Foil is 35 μ m(1oz) ● Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 			<p>Used for 3pcs Xeon 1 Power Series, eg:OSW4XME1C1E</p>
<p>RGB</p>	<p>OSMCPCB8060C</p>	<ul style="list-style-type: none"> ● Aluminum metal-base copper-clad laminate PCB ● Design for Xeon 1 Power RGB Series LED ● Base metal is 1.5mm Aluminum ● With HTCD Thermally Conductive Dielectric to suitable high power LED ● Copper Circuit Foil is 35 μ m(1oz) ● Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	 <p>Unit:mm Tolerance:±0.30mm</p>		<p>Used for Xeon 1 Power RGB Series, eg:OSTCXBEAC1E</p>

Heat Sink for Tops Power Series					
Item	Part Number	Description	Dimension	Photo	Application
1W	OSMCPCB5050B	<ul style="list-style-type: none"> Aluminum metal-base copper-clad laminate PCB Design for Tops 1 Power Series LED Base metal is 1.5mm Aluminum With NTC Thermally Conductive Dielectric Copper Circuit Foil is 35 μ m (1oz) Surface Finish is Black Solder Mask, Pb-free HASL solder pads (RoHS compliant) 			Used for Tops 1 Power Series, eg: OSW4XAT1C1E
3W	OSMCPCB5050C	<ul style="list-style-type: none"> Aluminum metal-base copper-clad laminate PCB Design for Tops 3 Power Series LED Base metal is 1.5mm Aluminum With HTCD Thermally Conductive Dielectric to suitable high power LED Copper Circuit Foil is 35 μ m (1oz) Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 			Used for Tops 3 Power Series, eg: OSW4XAT3C1E

RGB	OSMCPCB5050A	<ul style="list-style-type: none"> Aluminum metal-base copper-clad laminate PCB Design for Tops 0.5 Power RGB Series LED Base metal is 1.5mm Aluminum With HTCD Thermally Conductive Dielectric to suitable high power LED Copper Circuit Foil is 35 μ m(1oz) Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	 <p>Unit:mm Tolerance:±0.30mm</p>		<p>Used for Tops 0.5 Power RGB Series, eg: OSTCXBTHC1E</p>
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Heat Sink for Commercial Series

Item	Part Number	Description	Dimension	Photo	Application
RGB	OSMCPCB9218A	<ul style="list-style-type: none"> Aluminum metal-base copper-clad laminate PCB Design for Commercial 1 Power RGB Series LED Base metal is 1.5mm Aluminum With HTCD Thermally Conductive Dielectric to suitable high power LED Copper Circuit Foil is 35 μ m(1oz) Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	 <p>Unit:mm Tolerance:±0.30mm</p>		<p>Used for Commercial 1 Power RGB Series, eg: OSTCXBC1C1E</p>

Appendix

Data and information for MCPCB

Items	Unit	Reference
Thermal Conductivity	W/mK	0.8W/mK
Dielectric thickness	μ m	100
Breakdown voltage	kV(DC)	> 3kV
Insulation resistance		10 ⁵
Maximum Working Temperature		130
Peel Strength	N/mm	> 1.4
Blistering after heat shock within 1 minutes		<260
Copper thickness	μ m	35
Base metal plate	-	Aluminum
Base metal thickness	mm	1.5